

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
06	153	FR4	35	L36.35	P18_06	blind 01-02

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_153_FR4_35_L36.35_p18_06_blind_01-02

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-2	35 μ	Copper		
	360 μ	L-FR4		
	35 μ	Copper		
Layer-3	35 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-4	35 μ	Copper		
	360 μ	L-FR4		
	35 μ	Copper		
Layer-5	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-99	35 μ	Copper		

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